

IN THE CLAIMS

Each claim of the present application is set forth below with a parenthetical notation immediately following the claim number indicating the current claim status. The Examiner's entry of the claim amendments, as shown in marked-up form is respectfully requested.

1. (CURRENTLY AMENDED) A method for depositing material on a semiconductor wafer, wherein the wafer temperature is maintained within a temperature range, the method comprising:

providing a target comprising the material to be deposited;

supporting the wafer in a spaced-apart relation from with a chuck, wherein the wafer is positioned between the target and the chuck;

controlling a chuck temperature to ~~raise~~ control the wafer temperature to within the temperature range, ~~in the absence of an active cooling mechanism between the wafer and the chuck, and wherein a~~ the chuck temperature is greater than a the wafer temperature causing

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